



---

**TO: ALL PERICOM CUSTOMERS**

**SUBJECT: Sumitomo Epoxy Mold Compound Issue – EME7351UT**

Pericom's current plastic encapsulated, Surface Mount Technology (SMT) packaged peripheral leaded products do not utilize Sumitomo's EME7351UT mold compound. This epoxy uses a Particled Phosphorus Flame Retardant Agent, which was found by some customers of other semiconductor industry suppliers to cause lead to lead shorts when the material became lodged between leads. Sumitomo created this newer compound in order to have an environmentally "green" product to meet worldwide demands for elimination of hazardous materials. Sumitomo is now using an Organic Type Phosphorus Flame Retardant Agent in this series of mold compounds, identified as EME7351US. They expect this to eliminate any possibility of the shorts between leads, but Pericom will not utilize it until it has been thoroughly proven over a period of at least one year.

Pericom currently uses Sumitomo's standard EME7351LS mold compound for many of our thin SMT products, which does not use any type of phosphorus as a flame retardant

If there are any questions or more information needed on this issue, please contact me at your convenience.

Regards,

Edward J. Mello  
Director, Quality Systems  
Pericom Semiconductor Corporation  
Phone: (408) 435-0800 Ext. 207  
Internet E-mail: emello@pericom.com